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Dimensions	
Chip Size	2225
L	5.6mm +/-0.4mm
W	6.4mm +/-0.4mm
T	1.4mm +/-0.15mm
B	0.6mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

General Information	
Series	SMD Comm X7R Tip-Ring
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Tin Termination
Features	Tin Termination
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	350 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	1uF
Measurement Condition	1kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	1 GOhms

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